

Amendments to the Specification:

Please replace the paragraph beginning at page 2, line 15 with the following rewritten paragraph:

--A type of microcomputer heat dissipation system comprising a power supply heat dissipation system and a circulation-based heat dissipation system inside a microcomputer chassis, which is characterized in that the above-mentioned circulation-based heat dissipation system employs a plurality of heat-absorbing units that can be disposed on heat-generating electrical components inside the microcomputer, and in that the said heat-absorbing units, via appropriate connection of pipework in series or in parallel, are in communication with a fluid circulating unit, and, to said fluid circulating unit, there can be serially connected at least a heat-radiating pipe bondable to a heat-radiating plate, with said heat-radiating plate disposed on the outer wall surface of the chassis. In the above-mentioned power supply heat dissipation system, the high-power transistors of the microcomputer power supply unit are connected to the heat-radiating plate via a heat-conducting device such as a metal heat transfer plate by means of planar contact, with said heat-radiating plate disposed on the outer wall surface of the chassis.--

Please replace the paragraph beginning at page 4, line 26 with the following rewritten paragraph:

--FIG. 2 is a structural drawing of Application Example 1, wherein the external wall surface of a top panel located in the top portion of microcomputer chassis (9) has a recess used to receive a heat transfer pipe (2) and a heat-radiating plate (3), with the top surface of the heat

*Cond P2*

transfer pipe (2) disposed in contact with the bottom surface of the heat-radiating plate (3). The heat-radiating plate (3) is integrally attached to the top panel in the top portion of the microcomputer chassis. The bottom face of the casing of a fluid-circulating pump (1) is integrally attached to the bottom face of the chassis through through the medium of the shock-absorbing device. Heat-absorbing units (5) are integrally bonded to heat-generating components in the microcomputer, and heat-absorbing units (7) are integrally bonded to high-power transistors (19-2) on the power supply unit's printed circuit board (10). Made of metal, the heat-radiating plate (3) has a smooth flat face on one side and parallel ribs on the other side.--

Please replace the paragraph beginning at page 8, line 8 with the following rewritten paragraph:

*P3*

--FIG. 10 is a structural drawing illustrating Application Example 4, wherein the external wall surface of a top panel located in the top portion of a microcomputer chassis (9) has two recesses, a front and rear recess, of which one is used to receive a heat transfer pipe (2) and a heat-radiating plate (3), and the other recess is used to receive a power supply heat dissipation system (19) and a power supply heat-radiating plate (19 20).--

Please replace the paragraph beginning at page 9, line 12 with the following rewritten paragraph:

*P4*

--FIG. 12 is a structural drawing illustrating the power supply heat dissipation system in Application Example 4, wherein the heat-generating surfaces of the high-power transistors (19-2)

of the power supply unit are bonded to one of the faces of a heat-conducting device such as a metal heat transfer plate (19-1), with the other face of the heat transfer plate (19-1) bonded to the bottom face of the power supply heat-radiating plate (20). The bases of the high-power transistors (19-2) are soldered to a circuit board (19-3). One side of the circuit printed on the circuit board (19-3) is connected to the bases of the high-power transistors and the other side is connected to a connector socket (19-4) soldered to the circuit board (19-3), and then, via a connector plug (19-5) and a wire belt (19-6) attached to the plug (19-5), is further connected to the location where the high-power transistors (19-2) are soldered to the circuit board (19-3) of the power supply unit.--